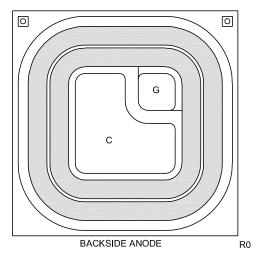


### **PROCESS DETAILS**

Process	GLASS PASSIVATED MESA
Die Size	41 x 41 MILS
Die Thickness	8.7 MILS ± 0.6 MILS
Cathode Bonding Pad Area	18 x 8 MILS
Gate Bonding Pad Area	7.1 x 7.1 MILS
Top Side Metalization	AI - 45,000Å
Back Side Metalization	Al/Mo/Ni/Ag - 20,000Å/5,000Å/5,000Å/2,000Å

### GEOMETRY



## **GROSS DIE PER 4 INCH WAFER**

6,474

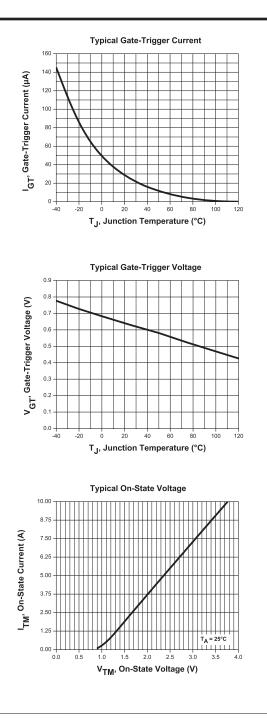
## PRINCIPAL DEVICE TYPES

CS18D BRX49 CS92D CS89M

R3 (22-March 2010)

## **PROCESS CPS041** Typical Electrical Characteristics

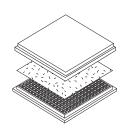






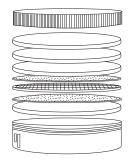
## **BARE DIE PACKING OPTIONS**





#### BARE DIE IN TRAY (WAFFLE) PACK

- CT: Singulated die in tray (waffle) pack. (example: CP211-PART NUMBER-CT)
- **CM**: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes). (example: CP211-PART NUMBER-CM)

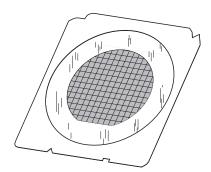


#### **UNSAWN WAFER**

WN: Full wafer, unsawn, 100% tested with reject die inked. (example: CP211-PART NUMBER-WN)

### SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring, 100% tested with reject die inked. (example: CP211-<u>PART NUMBER</u>-WR)



### SAWN WAFER ON METAL FRAME

WS: Full wafer, sawn and mounted on metal frame, 100% tested with reject die inked. (example: CP211-<u>PART NUMBER</u>-WS)

R0 (7-December 2015)

### **OUTSTANDING SUPPORT AND SUPERIOR SERVICES**



#### **PRODUCT SUPPORT**

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options

- Custom bar coding for shipments
- Custom product packing

#### DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2<sup>nd</sup> day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

#### CONTACT US

#### **Corporate Headquarters & Customer Support Team**

Central Semiconductor Corp. 145 Adams Avenue Hauppauge, NY 11788 USA Main Tel: (631) 435-1110 Main Fax: (631) 435-1824 Support Team Fax: (631) 435-3388 www.centralsemi.com

Worldwide Field Representatives: www.centralsemi.com/wwreps

Worldwide Distributors: www.centralsemi.com/wwdistributors

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http://www.centralsemi.com

# Product End of Life Notification

PDN ID:	PDN01059
Notification Date:	1/13/17
Last Buy Date:	N/A
Last Shipment Date	N/A

# Please be advised that Central Semiconductor must immediately discontinue the product(s) listed in the attached PDN notice. We are unable to accept any further orders for these products **unless** we have available inventory on hand.

You may have purchased one or more of the products listed. Please do not hesitate to contact your local Central Semiconductor sales representative with any questions or needs you may have. Central regrets any inconvenience this may cause.

Sincerely,

Central Semiconductor Corp.

DISCLAIMER: This End of Life (EOL) notification is in accordance with JEDEC standard JESD48 - Product Discontinuance. Central Semiconductor Corp. will make every effort to offer life-time buy (LTB) opportunities and/or offer replacement devices to existing customers for discontinued devices, however, one or both may not be possible for all devices. Please contact your local Central Semiconductor sales representative for LTB opportunities/additional information.



# Product End of Life Notification

PDN ID:	PDN01059
Notification Date:	1/13/17
Last Buy Date:	N/A
Last Shipment Date	N/A

Summary: The CPS041 wafer process has been discontinued; the devices below are now classified as End of Life (EOL).

Although Central Semiconductor Corp. makes every effort to continue to produce devices that have been proclaimed EOL (End of Life) by various manufacturers, it is an accepted industry practice to discontinue certain devices when customer demand falls below a minimum level of sustainability. Accordingly, the following product(s) have been transitioned to End of Life status as part of Central's Product Management Process. Any replacement product will be noted below. The effective date for placing the last purchase order will be six(6) months from the date of this notice and twelve(12) months from the notice date for final shipments; this may be extended if inventory is available.

Central Part Number	Replacement
CPS041-CS18B-WN	CPS053-CS18B-WN
CPS041-2N5060-CT	CPS053-2N5060-CT
CPS041-2N5064-CT	CPS053-2N5064-CT
CPS041-2N5064-WN	CPS053-2N5064-WN
CPS041-2N878-CT	CPS053-2N878-CT
CPS041-2N878-WN	CPS053-2N878-WN

Central would be happy to assist you by providing additional information or technical data to help locate an alternate source if we have no replacement available. Please email your requests to engineering@centralsemi.com.

DISCLAIMER: This End of Life (EOL) notification is in accordance with JEDEC standard JESD48 - Product Discontinuance. Central Semiconductor Corp. will make every effort to offer life-time buy (LTB) opportunities and/or offer replacement devices to existing customers for discontinued devices, however, one or both may not be possible for all devices. Please contact your local Central Semiconductor sales representative for LTB opportunities/additional information.